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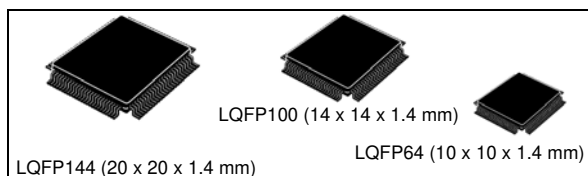
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## 32-bit MCU family built on the Power Architecture® for automotive body electronics applications

Datasheet - production data



### Features

- High-performance 64 MHz e200z0h CPU
  - 32-bit Power Architecture® technology
  - Up to 60 DMIPs operation
  - Variable length encoding (VLE)
- Memory
  - Up to 512 KB Code Flash with ECC
  - 64 KB Data Flash with ECC
  - Up to 48 KB SRAM with ECC
  - 8-entry memory protection unit (MPU)
- Interrupts
  - 16 priority levels
  - Non-maskable interrupt (NMI)
  - Up to 34 external interrupts incl. 18 wakeup lines
- GPIO: 45(LQFP64), 75(LQFP100), 123(LQFP144)
- Timer units
  - 6-channel 32-bit periodic interrupt timers
  - 4-channel 32-bit system timer module
  - Software watchdog timer
  - Real-time clock timer
- 16-bit counter time-triggered I/Os
  - Up to 56 channels with PWM/MC/IC/OC
  - ADC diagnostic via CTU
- Communications interface
  - Up to 6 FlexCAN interfaces (2.0B active) with 64-message objects each
  - Up to 4 LINFlex/UART
  - 3 DSPI / I2C
- Single 5 V or 3.3 V supply
- 10-bit analog-to-digital converter (ADC) with up to 36 channels
  - Extendable to 64 channels via external multiplexing
  - Individual conversion registers
  - Cross triggering unit (CTU)
- Dedicated diagnostic module for lighting
  - Advanced PWM generation
  - Time-triggered diagnostic
  - PWM-synchronized ADC measurements
- Clock generation
  - 4 to 16 MHz fast external crystal oscillator (FXOSC)
  - 32 kHz slow external crystal oscillator (SXOSC)
  - 16 MHz fast internal RC oscillator (FIRC)
  - 128 kHz slow internal RC oscillator (SIRC)
  - Software-controlled FMPLL
  - Clock monitor unit (CMU)
- Exhaustive debugging capability
  - Nexus1 on all devices
  - Nexus2+ available on emulation package (LBGA208)
- Low power capabilities
  - Ultra-low power standby with RTC, SRAM and CAN monitoring
  - Fast wakeup schemes
- Operating temp. range up to -40 to 125 °C

**Table 1. Device summary**

Package	Part number			
	256 KB code Flash memory		512 KB code Flash memory	
LQFP144	SPC560B40L5	—	SPC560B50L5	—
LQFP100	SPC560B40L3	SPC560C40L3	SPC560B50L3	SPC560C50L3
LQFP64 <sup>(1)</sup>	SPC560B40L1	SPC560C40L1	SPC560B50L1	SPC560C50L1

1. All LQFP64 information is indicative and must be confirmed during silicon validation.

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# 1 Introduction

## 1.1 Document overview

This document describes the features of the family and options available within the family members, and highlights important electrical and physical characteristics of the device. To ensure a complete understanding of the device functionality, refer also to the device reference manual and errata sheet.

## 1.2 Description

The SPC560B40x/50x and SPC560C40x/50x is a family of next generation microcontrollers built on the Power Architecture embedded category.

The SPC560B40x/50x and SPC560C40x/50x family of 32-bit microcontrollers is the latest achievement in integrated automotive application controllers. It belongs to an expanding family of automotive-focused products designed to address the next wave of body electronics applications within the vehicle. The advanced and cost-efficient host processor core of this automotive controller family complies with the Power Architecture embedded category and only implements the VLE (variable-length encoding) APU, providing improved code density. It operates at speeds of up to 64 MHz and offers high performance processing optimized for low power consumption. It capitalizes on the available development infrastructure of current Power Architecture devices and is supported with software drivers, operating systems and configuration code to assist with users implementations.

**Table 2. SPC560B40x/50x and SPC560C40x/50x device comparison<sup>(1)</sup>**

Feature	Device										
	SPC560B 40L1	SPC560B 40L3	SPC560B 40L5	SPC560C 40L1	SPC560C 40L3	SPC560B 50L1	SPC560B 50L3	SPC560B 50L5	SPC560C 50L1	SPC560C 50L3	SPC560B 50B2
CPU	e200z0h										
Execution speed <sup>(2)</sup>	Static – up to 64 MHz										
Code Flash	256 KB					512 KB					
Data Flash	64 KB (4 × 16 KB)										
RAM	24 KB			32 KB		32 KB			48 KB		
MPU	8-entry										
ADC (10-bit)	12 ch	28 ch	36 ch	8 ch	28 ch	12 ch	28 ch	36 ch	8 ch	28 ch	36 ch
CTU	Yes										
Total timer I/O <sup>(3)</sup>	12 ch,	28 ch,	56 ch,	12 ch,	28 ch,	12 ch,	28 ch,	56 ch,	12 ch,	28 ch,	56 ch,
eMIOS	16-bit	16-bit	16-bit	16-bit	16-bit	16-bit	16-bit	16-bit	16-bit	16-bit	16-bit
– PWM + MC + IC/OC <sup>(4)</sup>	2 ch	5 ch	10 ch	2 ch	5 ch	2 ch	5 ch	10 ch	2 ch	5 ch	10 ch
– PWM + IC/OC <sup>(4)</sup>	10 ch	20 ch	40 ch	10 ch	20 ch	10 ch	20 ch	40 ch	10 ch	20 ch	40 ch
– IC/OC <sup>(4)</sup>	—	3 ch	6 ch	—	3 ch	—	3 ch	6 ch	—	3 ch	6 ch
SCI (LINFlex)	3 <sup>(5)</sup>			4							
SPI (DSPI)	2	3		2	3	2	3		2	3	
CAN (FlexCAN)	2 <sup>(6)</sup>			5	6	3 <sup>(7)</sup>			5	6	
I <sup>2</sup> C	1										
32 kHz oscillator	Yes										
GPIO <sup>(8)</sup>	45	79	123	45	79	45	79	123	45	79	123



**Table 2. SPC560B40x/50x and SPC560C40x/50x device comparison<sup>(1)</sup> (continued)**

Feature	Device										
	SPC560B 40L1	SPC560B 40L3	SPC560B 40L5	SPC560C 40L1	SPC560C 40L3	SPC560B 50L1	SPC560B 50L3	SPC560B 50L5	SPC560C 50L1	SPC560C 50L3	SPC560B 50B2
Debug	JTAG										Nexus2+
Package	LQFP64 <sup>(9)</sup>	LQFP100	LQFP144	LQFP64 <sup>(9)</sup>	LQFP100	LQFP64 <sup>(9)</sup>	LQFP100	LQFP144	LQFP64 <sup>(9)</sup>	LQFP100	LPGA208 <sup>(10)</sup>

1. Feature set dependent on selected peripheral multiplexing—table shows example implementation.
2. Based on 125 °C ambient operating temperature.
3. See the eMIOS section of the device reference manual for information on the channel configuration and functions.
4. IC – Input Capture; OC – Output Compare; PWM – Pulse Width Modulation; MC – Modulus counter.
5. SCI0, SCI1 and SCI2 are available. SCI3 is not available.
6. CAN0, CAN1 are available. CAN2, CAN3, CAN4 and CAN5 are not available.
7. CAN0, CAN1 and CAN2 are available. CAN3, CAN4 and CAN5 are not available.
8. I/O count based on multiplexing with peripherals.
9. All LQFP64 information is indicative and must be confirmed during silicon validation.
10. LPGA208 available only as development package for Nexus2+.

## 2 Block diagram

*Figure 1* shows a top-level block diagram of the SPC560B40x/50x and SPC560C40x/50x device series.

Figure 1. SPC560B40x/50x and SPC560C40x/50x block diagram

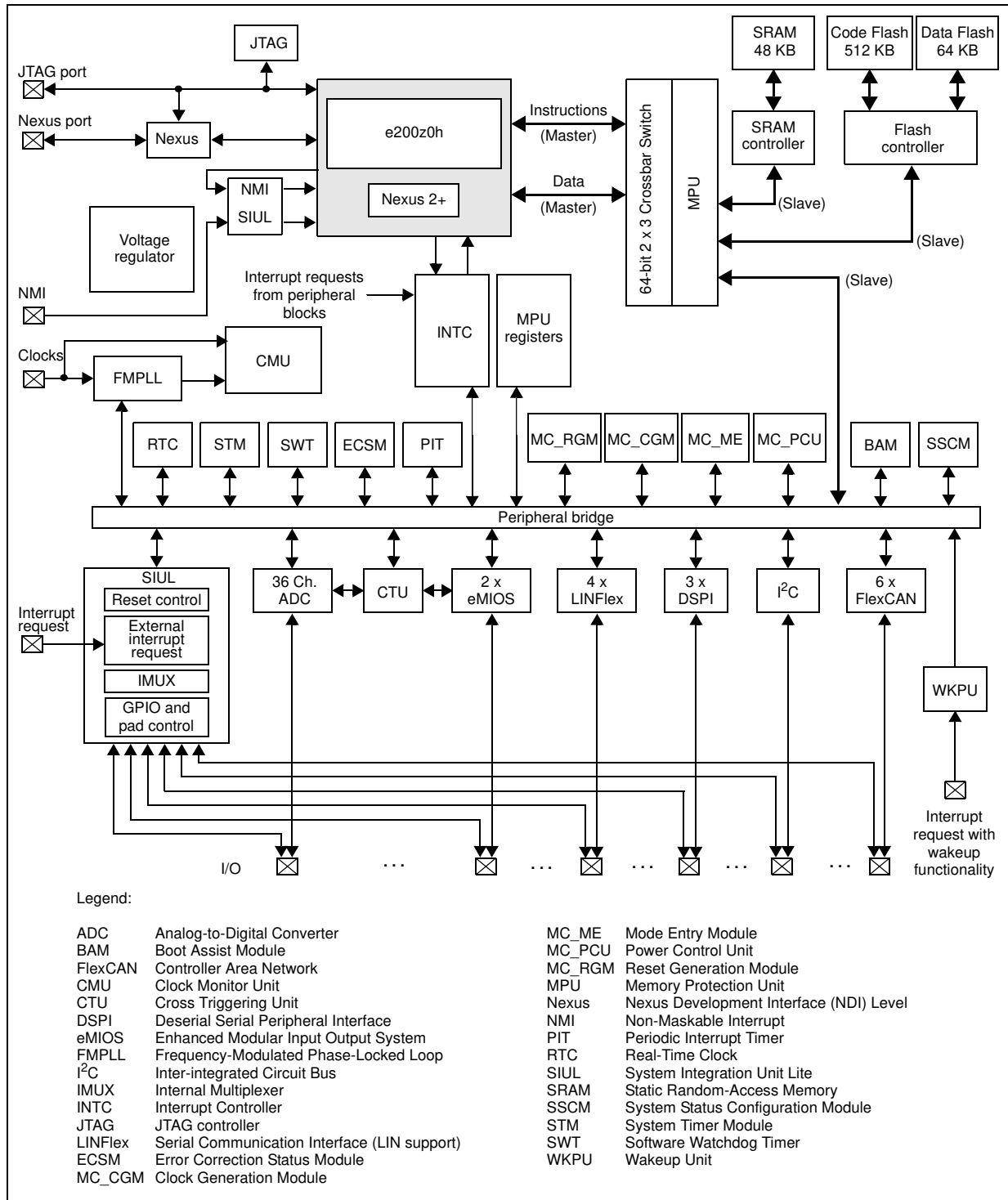


Table 3 summarizes the functions of all blocks present in the SPC560B40x/50x and SPC560C40x/50x series of microcontrollers. Please note that the presence and number of blocks vary by device and package.

**Table 3. SPC560B40x/50x and SPC560C40x/50x series block summary**

Block	Function
Analog-to-digital converter (ADC)	Multi-channel, 10-bit analog-to-digital converter
Boot assist module (BAM)	A block of read-only memory containing VLE code which is executed according to the boot mode of the device
Clock monitor unit (CMU)	Monitors clock source (internal and external) integrity
Cross triggering unit (CTU)	Enables synchronization of ADC conversions with a timer event from the eMIOS or from the PIT
Deserial serial peripheral interface (DSPI)	Provides a synchronous serial interface for communication with external devices
Error Correction Status Module (ECSM)	Provides a myriad of miscellaneous control functions for the device including program-visible information about configuration and revision levels, a reset status register, wakeup control for exiting sleep modes, and optional features such as information on memory errors reported by error-correcting codes
Enhanced Direct Memory Access (eDMA)	Performs complex data transfers with minimal intervention from a host processor via “n” programmable channels.
Enhanced modular input output system (eMIOS)	Provides the functionality to generate or measure events
Flash memory	Provides non-volatile storage for program code, constants and variables
FlexCAN (controller area network)	Supports the standard CAN communications protocol
Frequency-modulated phase-locked loop (FMPLL)	Generates high-speed system clocks and supports programmable frequency modulation
Internal multiplexer (IMUX) SIU subblock	Allows flexible mapping of peripheral interface on the different pins of the device
Inter-integrated circuit (I <sup>2</sup> C™) bus	A two wire bidirectional serial bus that provides a simple and efficient method of data exchange between devices
Interrupt controller (INTC)	Provides priority-based preemptive scheduling of interrupt requests
JTAG controller	Provides the means to test chip functionality and connectivity while remaining transparent to system logic when not in test mode
LINFlex controller	Manages a high number of LIN (Local Interconnect Network protocol) messages efficiently with a minimum of CPU load
Clock generation module (MC_CGM)	Provides logic and control required for the generation of system and peripheral clocks
Mode entry module (MC_ME)	Provides a mechanism for controlling the device operational mode and mode transition sequences in all functional states; also manages the power control unit, reset generation module and clock generation module, and holds the configuration, control and status registers accessible for applications
Power control unit (MC_PCU)	Reduces the overall power consumption by disconnecting parts of the device from the power supply via a power switching device; device components are grouped into sections called “power domains” which are controlled by the PCU
Reset generation module (MC_RGM)	Centralizes reset sources and manages the device reset sequence of the device

Table 3. SPC560B40x/50x and SPC560C40x/50x series block summary (continued)

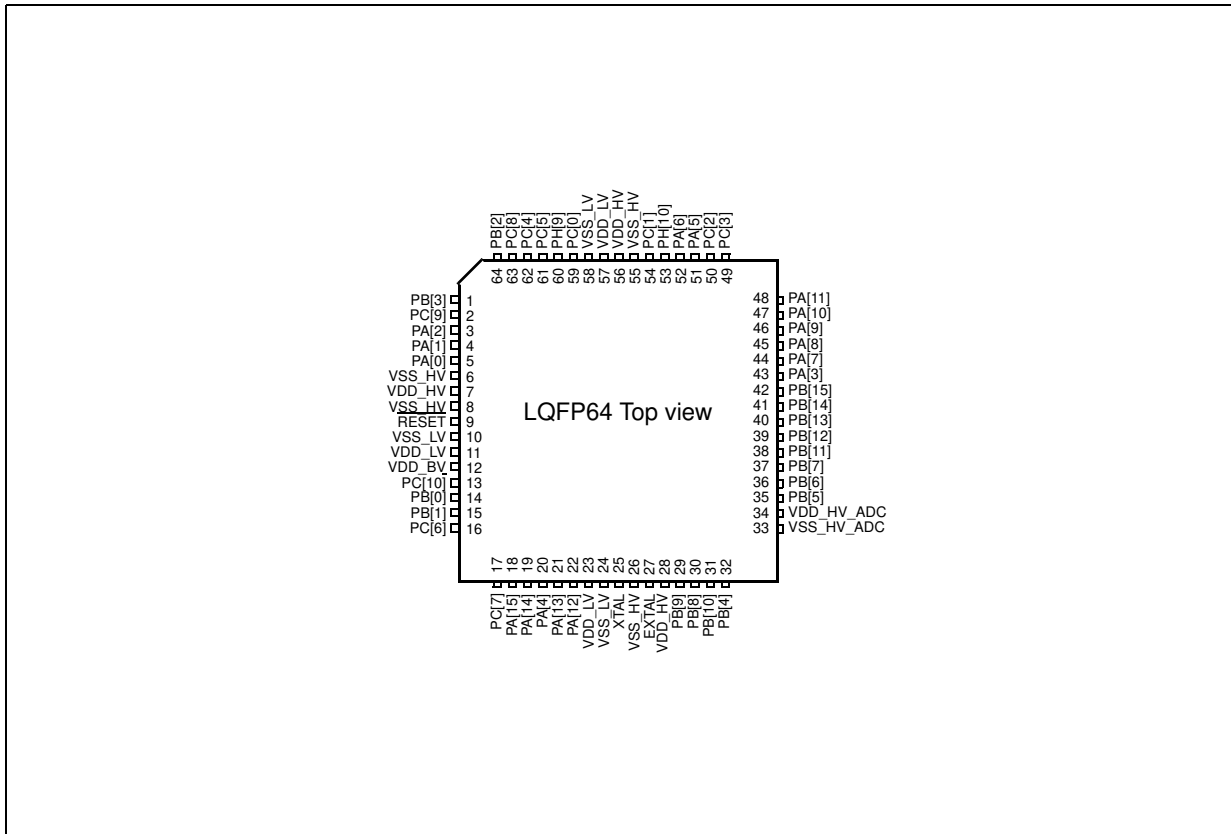
Block	Function
Memory protection unit (MPU)	Provides hardware access control for all memory references generated in a device
Nexus development interface (NDI)	Provides real-time development support capabilities in compliance with the IEEE-ISTO 5001-2003 standard
Periodic interrupt timer (PIT)	Produces periodic interrupts and triggers
Real-time counter (RTC)	A free running counter used for time keeping applications, the RTC can be configured to generate an interrupt at a predefined interval independent of the mode of operation (run mode or low-power mode)
System integration unit (SIU)	Provides control over all the electrical pad controls and up to 32 ports with 16 bits of bidirectional, general-purpose input and output signals and supports up to 32 external interrupts with trigger event configuration
Static random-access memory (SRAM)	Provides storage for program code, constants, and variables
System status configuration module (SSCM)	Provides system configuration and status data (such as memory size and status, device mode and security status), device identification data, debug status port enable and selection, and bus and peripheral abort enable/disable
System timer module (STM)	Provides a set of output compare events to support AUTOSAR (Automotive Open System Architecture) and operating system tasks
Software watchdog timer (SWT)	Provides protection from runaway code
Wakeup unit (WKPU)	The wakeup unit supports up to 18 external sources that can generate interrupts or wakeup events, of which 1 can cause non-maskable interrupt requests or wakeup events.
Crossbar (XBAR) switch	Supports simultaneous connections between two master ports and three slave ports. The crossbar supports a 32-bit address bus width and a 64-bit data bus width.

### 3 Package pinouts and signal descriptions

#### 3.1 Package pinouts

The available LQFP pinouts and the LPGA208 ballmap are provided in the following figures. For pin signal descriptions, please refer to the device reference manual (RM0017).

Figure 2. LQFP 64-pin configuration<sup>(a)</sup>



a. All LQFP64 information is indicative and must be confirmed during silicon validation.



Figure 3. LQFP 100-pin configuration

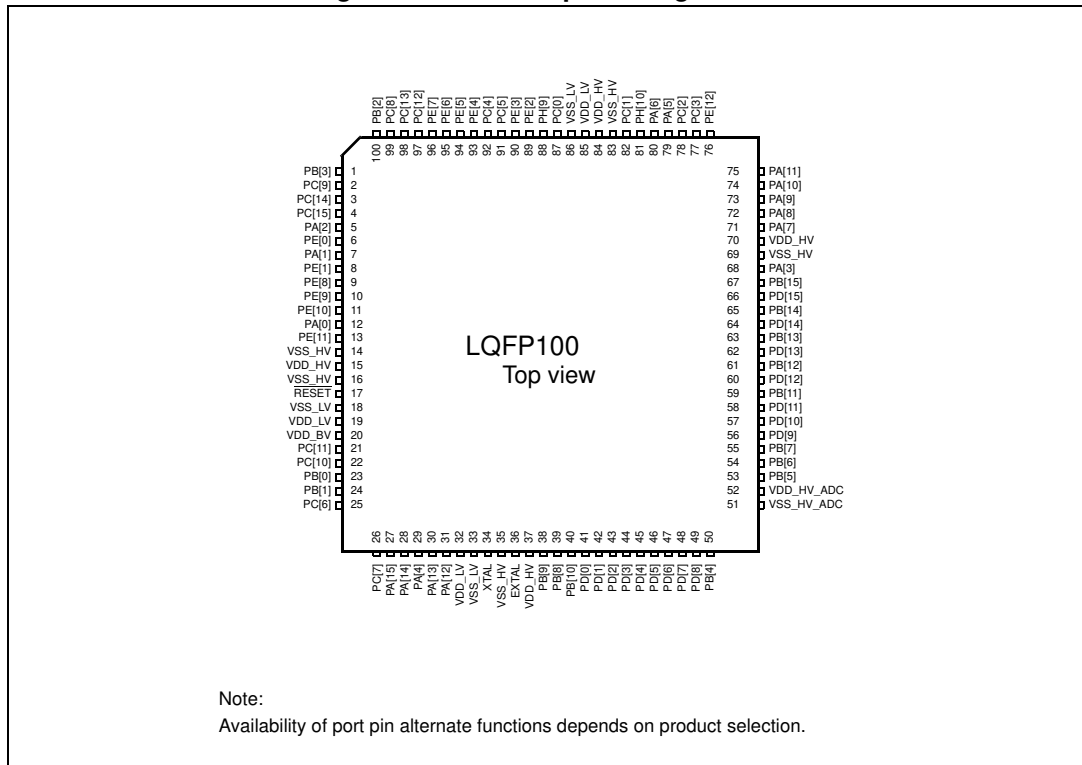


Figure 4. LQFP 144-pin configuration

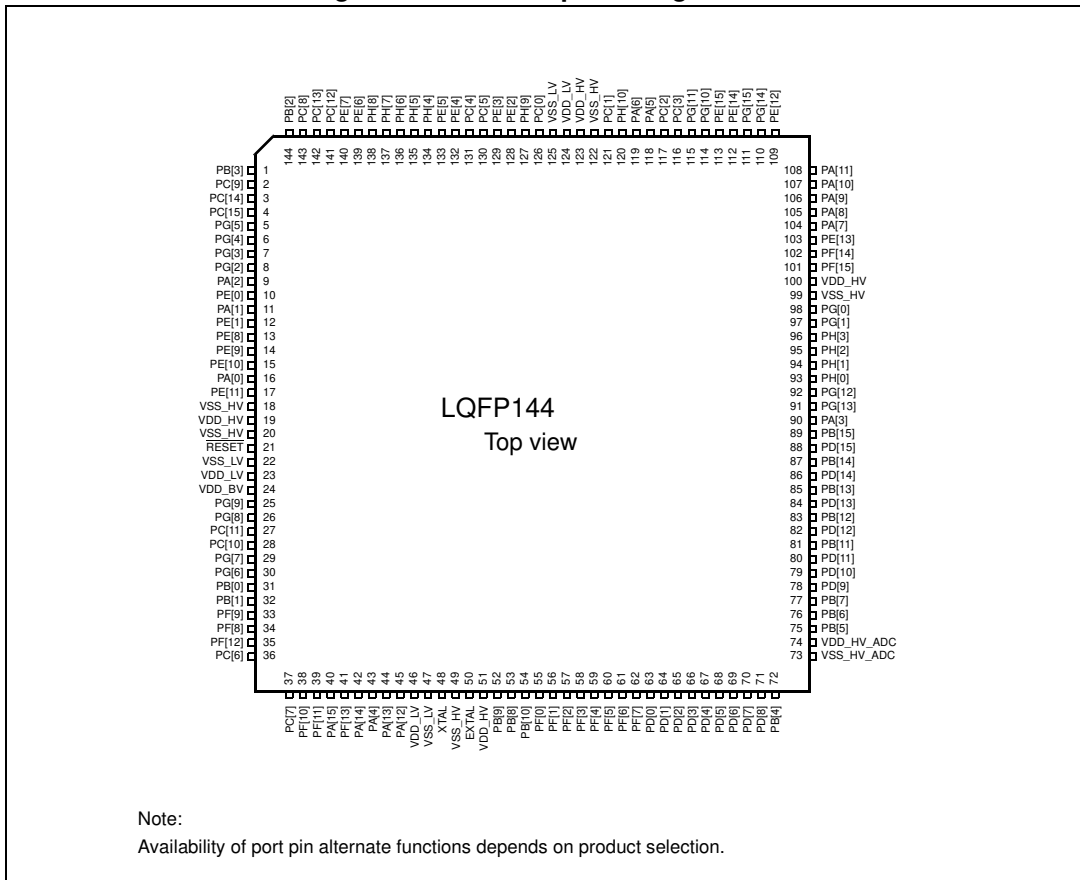


Figure 5. LBG208 configuration

	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16									
A	PC[8]	PC[13]	NC	NC	PH[8]	PH[4]	PC[5]	PC[0]	NC	NC	PC[2]	NC	PE[15]	NC	NC	NC	A								
B	PC[9]	PB[2]	NC	PC[12]	PE[6]	PH[5]	PC[4]	PH[9]	PH[10]	NC	PC[3]	PG[11]	PG[15]	PG[14]	PA[11]	PA[10]	B								
C	PC[14]	VDD_HV	PB[3]	PE[7]	PH[7]	PE[5]	PE[3]	VSS_LV	PC[1]	NC	PA[5]	NC	PE[14]	PE[12]	PA[9]	PA[8]	C								
D	NC	NC	PC[15]	NC	PH[6]	PE[4]	PE[2]	VDD_LV	VDD_HV	NC	PA[6]	NC	PG[10]	PF[14]	PE[13]	PA[7]	D								
E	PG[4]	PG[5]	PG[3]	PG[2]									PG[1]	PG[0]	PF[15]	VDD_HV	E								
F	PE[0]	PA[2]	PA[1]	PE[1]									PH[0]	PH[1]	PH[3]	PH[2]	F								
G	PE[9]	PE[8]	PE[10]	PA[0]									VSS_HV	VSS_HV	VSS_HV	VSS_HV	VDD_HV	NC	NC	MSEO	G				
H	VSS_HV	PE[11]	VDD_HV	NC									VSS_HV	VSS_HV	VSS_HV	VSS_HV	MDO3	MDO2	MDO0	MDO1	H				
J	RESET	VSS_LV	NC	NC									VSS_HV	VSS_HV	VSS_HV	VSS_HV	NC	NC	NC	NC	J				
K	EVTI	NC	VDD_BV	VDD_LV									VSS_HV	VSS_HV	VSS_HV	VSS_HV	NC	PG[12]	PA[3]	PG[13]	K				
L	PG[9]	PG[8]	NC	EVTO																	PB[15]	PD[15]	PD[14]	PB[14]	L
M	PG[7]	PG[6]	PC[10]	PC[11]																	PB[13]	PD[13]	PD[12]	PB[12]	M
N	PB[1]	PF[9]	PB[0]	NC	NC	PA[4]	VSS_LV	EXTAL	VDD_HV	PF[0]	PF[4]	NC	PB[11]	PD[10]	PD[9]	PD[11]	N								
P	PF[8]	NC	PC[7]	NC	NC	PA[14]	VDD_LV	XTAL	PB[10]	PF[1]	PF[5]	PD[0]	PD[3]	VDD_HV_ADC	PB[6]	PB[7]	P								
R	PF[12]	PC[6]	PF[10]	PF[11]	VDD_HV	PA[15]	PA[13]	NC	OSC32K_XTAL	PF[3]	PF[7]	PD[2]	PD[4]	PD[7]	VSS_HV_ADC	PB[5]	R								
T	NC	NC	NC	MCKO	NC	PF[13]	PA[12]	NC	OSC32K_EXTAL	PF[2]	PF[6]	PD[1]	PD[5]	PD[6]	PD[8]	PB[4]	T								
	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16									

1. Note: LBG208 available only as development package for Nexus 2+.

NC = Not connected

### 3.2 Pad configuration during reset phases

All pads have a fixed configuration under reset.

During the power-up phase, all pads are forced to tristate.

After power-up phase, all pads are forced to tristate with the following exceptions:

- PA[9] (FAB) is pull-down. Without external strong pull-up the device starts fetching from flash.
- PA[8] (ABS[0]) is pull-up.
- RESET pad is driven low. This is pull-up only after PHASE2 reset completion.
- JTAG pads (TCK, TMS and TDI) are pull-up whilst TDO remains tristate.
- Precise ADC pads (PB[7:4] and PD[11:0]) are left tristate (no output buffer available).
- Main oscillator pads (EXTAL, XTAL) are tristate.
- Nexus output pads (MDO[n], MCKO, EVTO, MSEO) are forced to output.

### 3.3 Voltage supply pins

Voltage supply pins are used to provide power to the device. Three dedicated VDD\_LV/VSS\_LV supply pairs are used for 1.2 V regulator stabilization.

**Table 4. Voltage supply pin descriptions**

Port pin	Function	Pin number			
		LQFP64	LQFP100	LQFP144	LBGA208 <sup>(1)</sup>
VDD_HV	Digital supply voltage	7, 28, 56	15, 37, 70, 84	19, 51, 100, 123	C2, D9, E16, G13, H3, N9, R5
VSS_HV	Digital ground	6, 8, 26, 55	14, 16, 35, 69, 83	18, 20, 49, 99, 122	G7, G8, G9, G10, H1, H7, H8, H9, H10, J7, J8, J9, J10, K7, K8, K9, K10
VDD_LV	1.2V decoupling pins. Decoupling capacitor must be connected between these pins and the nearest V <sub>SS_LV</sub> pin. <sup>(2)</sup>	11, 23, 57	19, 32, 85	23, 46, 124	D8, K4, P7
VSS_LV	1.2V decoupling pins. Decoupling capacitor must be connected between these pins and the nearest V <sub>DD_LV</sub> pin. <sup>(2)</sup>	10, 24, 58	18, 33, 86	22, 47, 125	C8, J2, N7
VDD_BV	Internal regulator supply voltage	12	20	24	K3
VSS_HV_ADC	Reference ground and analog ground for the ADC	33	51	73	R15
VDD_HV_ADC	Reference voltage and analog supply for the ADC	34	52	74	P14

1. LBGA208 available only as development package for Nexus2+

2. A decoupling capacitor must be placed between each of the three VDD\_LV/VSS\_LV supply pairs to ensure stable voltage (see the recommended operating conditions in the device datasheet for details).

### 3.4 Pad types

In the device the following types of pads are available for system pins and functional port pins:

S = Slow<sup>(b)</sup>

M = Medium<sup>(b) (c)</sup>

F = Fast<sup>(b) (c)</sup>

I = Input only with analog feature<sup>(b)</sup>

J = Input/Output ('S' pad) with analog feature

X = Oscillator

b. See the I/O pad electrical characteristics in the device datasheet for details.

### 3.5 System pins

The system pins are listed in [Table 5](#).

**Table 5. System pin descriptions**

System pin	Function	I/O direction	Pad type	RESET configuration	Pin number			
					LQFP64	LQFP100	LQFP144	LBGA208 <sup>(1)</sup>
RESET	Bidirectional reset with Schmitt-Trigger characteristics and noise filter.	I/O	M	Input, weak pull-up only after PHASE2	9	17	21	J1
EXTAL	Analog output of the oscillator amplifier circuit, when the oscillator is not in bypass mode. Analog input for the clock generator when the oscillator is in bypass mode. <sup>(2)</sup>	I/O	X	Tristate	27	36	50	N8
XTAL	Analog input of the oscillator amplifier circuit. Needs to be grounded if oscillator is used in bypass mode. <sup>(2)</sup>	I	X	Tristate	25	34	48	P8

1. LBGA208 available only as development package for Nexus2+
2. See the relevant section of the datasheet

### 3.6 Functional ports

The functional port pins are listed in [Table 6](#).

c. All medium and fast pads are in slow configuration by default at reset and can be configured as fast or medium (see PCR.SRC in section Pad Configuration Registers (PCR0–PCR122) in the device reference manual).

Table 6. Functional port pin descriptions

Port pin	PCR	Alternate function <sup>(1)</sup>	Function	Peripheral	I/O direction <sup>(2)</sup>	Pad type	RESET configuration	Pin number			
								LQFP64	LQFP100	LQFP144	LBGA208 <sup>(3)</sup>
PA[0]	PCR[0]	AF0 AF1 AF2 AF3 —	GPIO[0] E0UC[0] CLKOUT — WKPU[19] <sup>(4)</sup>	SIUL eMIOS_0 CGL — WKPU	I/O I/O O — I	M	Tristate	5	12	16	G4
PA[1]	PCR[1]	AF0 AF1 AF2 AF3 — —	GPIO[1] E0UC[1] — — NMI <sup>(5)</sup> WKPU[2] <sup>(4)</sup>	SIUL eMIOS_0 — — WKPU WKPU	I/O I/O — — I I	S	Tristate	4	7	11	F3
PA[2]	PCR[2]	AF0 AF1 AF2 AF3 —	GPIO[2] E0UC[2] — — WKPU[3] <sup>(4)</sup>	SIUL eMIOS_0 — — WKPU	I/O I/O — — I	S	Tristate	3	5	9	F2
PA[3]	PCR[3]	AF0 AF1 AF2 AF3 —	GPIO[3] E0UC[3] — — EIRQ[0]	SIUL eMIOS_0 — — SIUL	I/O I/O — — I	S	Tristate	43	68	90	K15
PA[4]	PCR[4]	AF0 AF1 AF2 AF3 —	GPIO[4] E0UC[4] — — WKPU[9] <sup>(4)</sup>	SIUL eMIOS_0 — — WKPU	I/O I/O — — I	S	Tristate	20	29	43	N6
PA[5]	PCR[5]	AF0 AF1 AF2 AF3	GPIO[5] E0UC[5] — —	SIUL eMIOS_0 — —	I/O I/O — —	M	Tristate	51	79	118	C11
PA[6]	PCR[6]	AF0 AF1 AF2 AF3 —	GPIO[6] E0UC[6] — — EIRQ[1]	SIUL eMIOS_0 — — SIUL	I/O I/O — — I	S	Tristate	52	80	119	D11



Table 6. Functional port pin descriptions (continued)

Port pin	PCR	Alternate function <sup>(1)</sup>	Function	Peripheral	I/O direction <sup>(2)</sup>	Pad type	RESET configuration	Pin number			
								LQFP64	LQFP100	LQFP144	LBGA208 <sup>(3)</sup>
PA[7]	PCR[7]	AF0 AF1 AF2 AF3 —	GPIO[7] E0UC[7] LIN3TX — EIRQ[2]	SIUL eMIOS_0 LINFlex_3 — SIUL	I/O I/O O — I	S	Tristate	44	71	104	D16
PA[8]	PCR[8]	AF0 AF1 AF2 AF3 — N/A <sup>(6)</sup> —	GPIO[8] E0UC[8] — — EIRQ[3] ABS[0] LIN3RX	SIUL eMIOS_0 — — SIUL BAM LINFlex_3	I/O I/O — — I I I	S	Input, weak pull-up	45	72	105	C16
PA[9]	PCR[9]	AF0 AF1 AF2 AF3 N/A <sup>(6)</sup>	GPIO[9] E0UC[9] — — FAB	SIUL eMIOS_0 — — BAM	I/O I/O — — I	S	Pull-down	46	73	106	C15
PA[10]	PCR[10]	AF0 AF1 AF2 AF3	GPIO[10] E0UC[10] SDA —	SIUL eMIOS_0 I2C_0 —	I/O I/O I/O —	S	Tristate	47	74	107	B16
PA[11]	PCR[11]	AF0 AF1 AF2 AF3	GPIO[11] E0UC[11] SCL —	SIUL eMIOS_0 I2C_0 —	I/O I/O I/O —	S	Tristate	48	75	108	B15
PA[12]	PCR[12]	AF0 AF1 AF2 AF3 —	GPIO[12] — — — SIN_0	SIUL — — — DSPI0	I/O — — — I	S	Tristate	22	31	45	T7
PA[13]	PCR[13]	AF0 AF1 AF2 AF3	GPIO[13] SOUT_0 — —	SIUL DSPI_0 — —	I/O O — —	M	Tristate	21	30	44	R7

Table 6. Functional port pin descriptions (continued)

Port pin	PCR	Alternate function <sup>(1)</sup>	Function	Peripheral	I/O direction <sup>(2)</sup>	Pad type	RESET configuration	Pin number			
								LQFP64	LQFP100	LQFP144	LBGA208 <sup>(3)</sup>
PA[14]	PCR[14]	AF0 AF1 AF2 AF3 —	GPIO[14] SCK_0 CS0_0 — EIRQ[4]	SIUL DSPI_0 DSPI_0 — SIUL	I/O I/O I/O — I	M	Tristate	19	28	42	P6
PA[15]	PCR[15]	AF0 AF1 AF2 AF3 —	GPIO[15] CS0_0 SCK_0 — WKPU[10] <sup>(4)</sup>	SIUL DSPI_0 DSPI_0 — WKPU	I/O I/O I/O — I	M	Tristate	18	27	40	R6
PB[0]	PCR[16]	AF0 AF1 AF2 AF3	GPIO[16] CAN0TX — —	SIUL FlexCAN_0 — —	I/O O — —	M	Tristate	14	23	31	N3
PB[1]	PCR[17]	AF0 AF1 AF2 AF3 — —	GPIO[17] — — — WKPU[4] <sup>(4)</sup> CAN0RX	SIUL — — — WKPU FlexCAN_0	I/O — — — I I	S	Tristate	15	24	32	N1
PB[2]	PCR[18]	AF0 AF1 AF2 AF3	GPIO[18] LIN0TX SDA —	SIUL LINFlex_0 I2C_0 —	I/O O I/O —	M	Tristate	64	100	144	B2
PB[3]	PCR[19]	AF0 AF1 AF2 AF3 — —	GPIO[19] — SCL — WKPU[11] <sup>(4)</sup> LIN0RX	SIUL — I2C_0 — WKPU LINFlex_0	I/O — I/O — I I	S	Tristate	1	1	1	C3
PB[4]	PCR[20]	AF0 AF1 AF2 AF3 —	GPIO[20] — — — GPI[0]	SIUL — — — ADC	I — — — I	I	Tristate	32	50	72	T16



Table 6. Functional port pin descriptions (continued)

Port pin	PCR	Alternate function <sup>(1)</sup>	Function	Peripheral	I/O direction <sup>(2)</sup>	Pad type	RESET configuration	Pin number			
								LQFP64	LQFP100	LQFP144	LBGA208 <sup>(3)</sup>
PB[5]	PCR[21]	AF0 AF1 AF2 AF3 —	GPIO[21] — — — GPI[1]	SIUL — — — ADC	I — — — I	I	Tristate	35	53	75	R16
PB[6]	PCR[22]	AF0 AF1 AF2 AF3 —	GPIO[22] — — — GPI[2]	SIUL — — — ADC	I — — — I	I	Tristate	36	54	76	P15
PB[7]	PCR[23]	AF0 AF1 AF2 AF3 —	GPIO[23] — — — GPI[3]	SIUL — — — ADC	I — — — I	I	Tristate	37	55	77	P16
PB[8]	PCR[24]	AF0 AF1 AF2 AF3 — —	GPIO[24] — — — — ANS[0] OSC32K_XTAL <sup>(7)</sup>	SIUL — — — — ADC SXOSC	I — — — — I I/O	I	Tristate	30	39	53	R9
PB[9]	PCR[25]	AF0 AF1 AF2 AF3 — —	GPIO[25] — — — — ANS[1] OSC32K_EXTAL <sup>(7)</sup>	SIUL — — — — ADC SXOSC	I — — — — I I/O	I	Tristate	29	38	52	T9
PB[10]	PCR[26]	AF0 AF1 AF2 AF3 — —	GPIO[26] — — — — ANS[2] WKPU[8] <sup>(4)</sup>	SIUL — — — — ADC WKPU	I/O — — — — I I	J	Tristate	31	40	54	P9

Table 6. Functional port pin descriptions (continued)

Port pin	PCR	Alternate function <sup>(1)</sup>	Function	Peripheral	I/O direction <sup>(2)</sup>	Pad type	RESET configuration	Pin number			
								LQFP64	LQFP100	LQFP144	LBGA208 <sup>(3)</sup>
PB[11] (8)	PCR[27]	AF0 AF1 AF2 AF3 —	GPIO[27] E0UC[3] — CS0_0 ANS[3]	SIUL eMIOS_0 — DSPI_0 ADC	I/O I/O — I/O I	J	Tristate	38	59	81	N13
PB[12]	PCR[28]	AF0 AF1 AF2 AF3 —	GPIO[28] E0UC[4] — CS1_0 ANX[0]	SIUL eMIOS_0 — DSPI_0 ADC	I/O I/O — O I	J	Tristate	39	61	83	M16
PB[13]	PCR[29]	AF0 AF1 AF2 AF3 —	GPIO[29] E0UC[5] — CS2_0 ANX[1]	SIUL eMIOS_0 — DSPI_0 ADC	I/O I/O — O I	J	Tristate	40	63	85	M13
PB[14]	PCR[30]	AF0 AF1 AF2 AF3 —	GPIO[30] E0UC[6] — CS3_0 ANX[2]	SIUL eMIOS_0 — DSPI_0 ADC	I/O I/O — O I	J	Tristate	41	65	87	L16
PB[15]	PCR[31]	AF0 AF1 AF2 AF3 —	GPIO[31] E0UC[7] — CS4_0 ANX[3]	SIUL eMIOS_0 — DSPI_0 ADC	I/O I/O — O I	J	Tristate	42	67	89	L13
PC[0] <sup>(9)</sup>	PCR[32]	AF0 AF1 AF2 AF3	GPIO[32] — TDI —	SIUL — JTAGC —	I/O — I —	M	Input, weak pull-up	59	87	126	A8
PC[1] <sup>(9)</sup>	PCR[33]	AF0 AF1 AF2 AF3	GPIO[33] — TDO <sup>(10)</sup> —	SIUL — JTAGC —	I/O — O —	M	Tristate	54	82	121	C9